



**DEFENSE LOGISTICS AGENCY**

DLA LAND AND MARITIME  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

IN REPLY  
REFER TO

DLA LAND AND MARITIME- VQ (VQE-11-021326 / Mr. Stone / 614-692-3022 / js)

October 28, 2010

SUBJECT: Notification of Qualification, MIL-PRF-31032; FSC 5998; CAGE Code 45032

Mr. Mike Lyrek  
Universal Circuits Inc.  
8860 Zachary Lane North  
Maple Grove, MN 55369-4524

Dear Mr. Lyrek:

Qualification of products is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and /2. The capabilities qualified for each base material and slash sheet indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is October 21, 2010.

<b>MANUFACTURER INFORMATION</b>  Universal Circuits 8860 Zachary Lane North Maple Grove, MN 55369-4524	<b>BASIC PLANT LOCATION</b>  Same	<b>CONTACT: Mike Lyrek</b> <b>PHONE: (763) 315-1706</b> <b>FAX: (763) 425-0999</b> <b>CAGE CODE: 45032</b>																														
<b>CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:</b> MIL-PRF-31032 /1, /2 <table border="0"> <tr><td>Base Materials</td><td>GI (Woven E-Glass, Polyimid Resin)</td></tr> <tr><td>Max. Panel Size</td><td>18" X 24"</td></tr> <tr><td>Max. Board Thickness</td><td>0.062"</td></tr> <tr><td>Min / Max Drilled Thru Hole</td><td>0.0138" / Not Specified</td></tr> <tr><td>Aspect Ratio</td><td>4.5 : 1</td></tr> <tr><td>Number of Layers</td><td>8</td></tr> <tr><td>Min. Conductor Width</td><td>0.007"</td></tr> <tr><td>Min. Conductor Spacing</td><td>0.006"</td></tr> <tr><td>Part Mounting</td><td>SMT</td></tr> <tr><td>Hole Preparation</td><td>Plasma Etchback,, Chemical Desmear</td></tr> <tr><td>Through Hole Metallization</td><td>Direct Metallization</td></tr> <tr><td>Copper Plating</td><td>Acid Copper</td></tr> <tr><td>Finish Systems</td><td>Hot Air Solder Level (HASL), Electroless Nickel Immersion Gold (ENIG), Electrolytic Ni/Au</td></tr> <tr><td>Solder Resist</td><td>LPI</td></tr> <tr><td>Alternate Construction</td><td>Foil Lamination</td></tr> </table>		Base Materials	GI (Woven E-Glass, Polyimid Resin)	Max. Panel Size	18" X 24"	Max. Board Thickness	0.062"	Min / Max Drilled Thru Hole	0.0138" / Not Specified	Aspect Ratio	4.5 : 1	Number of Layers	8	Min. Conductor Width	0.007"	Min. Conductor Spacing	0.006"	Part Mounting	SMT	Hole Preparation	Plasma Etchback,, Chemical Desmear	Through Hole Metallization	Direct Metallization	Copper Plating	Acid Copper	Finish Systems	Hot Air Solder Level (HASL), Electroless Nickel Immersion Gold (ENIG), Electrolytic Ni/Au	Solder Resist	LPI	Alternate Construction	Foil Lamination	<b>QUALIFICATION LETTER:</b>  VQE-10-019530 VQE-11-021326
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The test report number assigned to this qualification is 31032-2995-10. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI or CVI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. If you have any questions, please contact Mr. Jonathan Stone, (614) 692-3022 or [vqe.js@dla.mil](mailto:vqe.js@dla.mil).

Sincerely,



FOR

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualification Division

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